



Step 1.
KGD w/base Substrate

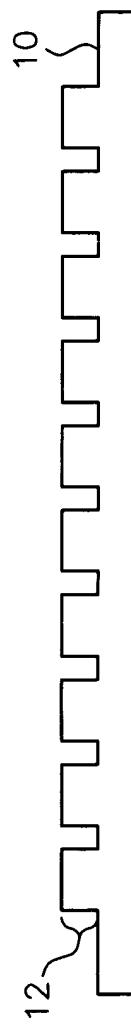


FIG. 2A

Step 2.
Deposition of
Photoresist Mask

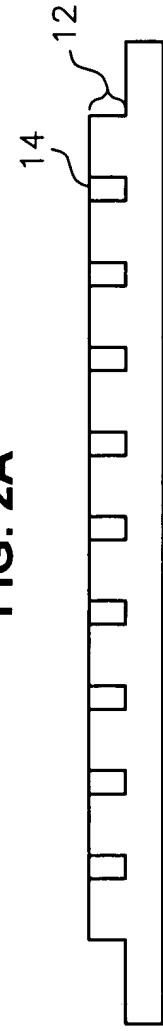


FIG. 2B

Step 3.
Add Back Grinding
Tape

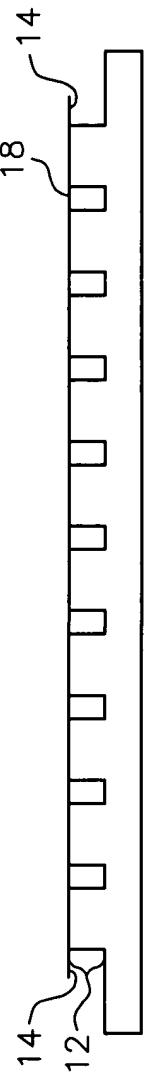


FIG. 2C

Step 4.
Grind Substrate and die
12

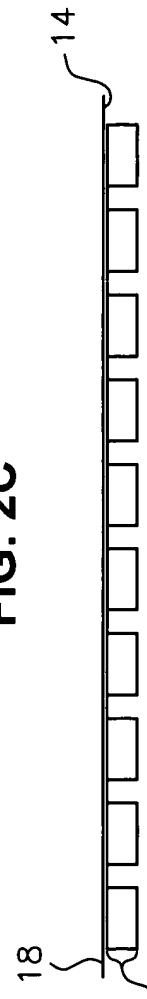


FIG. 2D

Step 5.
Apply UV Transfer Tape
to Backside of die
20



FIG. 2E

Step 6.
Remove Back Grinding
Tape and Photoresist mask
22



FIG. 2F